

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	"20050051903"	US-PGPUB; USPAT	OR	OFF	2005/04/07 22:50
L2	2214	(dual near inline near memory near module or DIMM)	US-PGPUB; USPAT	OR	OFF	2005/04/07 22:51
L3	18	(dual near inline near memory near module or DIMM) and dual near (semiconductor or die or chip or IC)	US-PGPUB; USPAT	OR	OFF	2005/04/07 22:54
L4	1770	(dual near inline near memory near module or DIMM) and (semiconductor or die or chip or IC)	US-PGPUB; USPAT	OR	OFF	2005/04/07 22:54
L5	888	(dual near inline near memory near module or DIMM) and (semiconductor or die or chip or IC)	USPAT	OR	OFF	2005/04/07 23:20
L6	269	257/747	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/07 23:20
L7	2554	257/692	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/07 23:29
L8	1679	257/693	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/07 23:45
L9	2250	257/698	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/07 23:59
L10	3527	257/723	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 00:18

L11	3326	257/737	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 00:36
L12	2	"20030001267"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 00:21
L13	3010	257/738	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 00:56
L14	4304	257/778	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 01:12
L15	0	257/E25.006	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 01:12
L16	2	257/E25.013	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 01:12
L17	2	257/E21.511	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 01:13
L18	4	257/E23.069	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 01:13

L19	1212	361/783	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 01:29
L20	1276	361/803	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 01:29
S1	5	"6081029".pn. or "5942794".pn. or "5623162".pn. or "5578871".pn. or "5371044".pn.	USPAT	OR	OFF	2005/04/06 13:16
S2	1	"6639306"	USPAT	OR	OFF	2004/06/22 14:25
S3	0	"20010033011"	USPAT	OR	OFF	2004/06/22 14:23
S4	1	"20010033011"	US-PGPUB; USPAT	OR	OFF	2004/06/22 14:23
S5	1	"4952999".PN.	USPAT	OR	OFF	2004/06/22 14:24
S6	1	"5371044".PN.	USPAT	OR	OFF	2004/06/22 14:24
S7	1	"5578871".PN.	USPAT	OR	OFF	2004/06/22 14:24
S8	1	"5623162".PN.	USPAT	OR	OFF	2004/06/22 14:24
S9	1	"5942794".PN.	USPAT	OR	OFF	2004/06/22 14:25
S10	1	"6081029".PN.	USPAT	OR	OFF	2004/06/22 14:25
S11	464	(semiconductor or die or chip or IC) and (die near pad or paddle) with (protru\$4 or tab)	USPAT	OR	ON	2004/06/22 15:07
S12	10	(semiconductor or die or chip or IC) and (die near pad or paddle) with (indentat\$4)	USPAT	OR	ON	2004/06/22 14:46
S13	5894	(semiconductor or die or chip or IC) and (lead) with (protru\$4 or tab or indentat\$3)	USPAT	OR	ON	2004/06/22 14:47
S14	909	((semiconductor or die or chip or IC) and (lead) with (protru\$4 or tab or indentat\$3)) and "438"/\$.ccls.	USPAT	OR	ON	2004/06/22 14:48
S15	1	"5389739".PN.	USPAT	OR	OFF	2004/06/22 14:49
S16	1	"5578871".PN.	USPAT	OR	OFF	2004/06/22 14:50
S17	1	"6303985".PN.	USPAT	OR	OFF	2004/06/22 14:50
S18	1	"4712129".PN.	USPAT	OR	OFF	2004/06/22 14:51
S19	1	"4803540".PN.	USPAT	OR	OFF	2004/06/22 14:51
S20	1	"4918511".PN.	USPAT	OR	OFF	2004/06/22 14:51
S21	1	"4952999".PN.	USPAT	OR	OFF	2004/06/22 14:55

S22	1	"5126820".PN.	USPAT	OR	OFF	2004/06/22 14:55
S23	1	"5214307".PN.	USPAT	OR	OFF	2004/06/22 14:55
S24	1	"5389739".PN.	USPAT	OR	OFF	2004/06/22 14:55
S25	1	"5578871".PN.	USPAT	OR	OFF	2004/06/22 14:55
S26	1	"5594234".PN.	USPAT	OR	OFF	2004/06/22 14:55
S27	1	"5610437".PN.	USPAT	OR	OFF	2004/06/22 14:56
S28	1	"5760465".PN.	USPAT	OR	OFF	2004/06/22 14:56
S29	1	"5796162".PN.	USPAT	OR	OFF	2004/06/22 14:56
S30	1	"5859471".PN.	USPAT	OR	OFF	2004/06/22 14:56
S31	1	"5864174".PN.	USPAT	OR	OFF	2004/06/22 14:56
S32	1	"5920114".PN.	USPAT	OR	OFF	2004/06/22 14:57
S33	1	"6075283".PN.	USPAT	OR	OFF	2004/06/22 14:57
S34	1	"6153924".PN.	USPAT	OR	OFF	2004/06/22 14:57
S35	112	(semiconductor or die or chip or IC) and (die near pad or paddle) with (protru\$4 or tab)	JPO	OR	ON	2004/06/22 15:16
S36	3151	257/666	USPAT	OR	ON	2004/06/22 15:18
S37	1	"5648682".PN.	USPAT	OR	OFF	2004/06/22 15:19
S38	1	"5677567".PN.	USPAT	OR	OFF	2004/06/22 15:19
S39	1	"6060769".PN.	USPAT	OR	OFF	2004/06/22 15:19
S40	1	"6208020".PN.	USPAT	OR	OFF	2004/06/22 15:19
S41	1	"5089878".PN.	USPAT	OR	OFF	2004/06/22 15:19
S42	1	"5977630".PN.	USPAT	OR	OFF	2004/06/22 15:19
S43	1	"6028350".PN.	USPAT	OR	OFF	2004/06/22 15:19
S44	1	"6047467".PN.	USPAT	OR	OFF	2004/06/22 15:19
S45	1	"6081029".PN.	USPAT	OR	OFF	2004/06/22 15:19
S46	1	"6130115".PN.	USPAT	OR	OFF	2004/06/22 15:19
S47	1	"6191494".PN.	USPAT	OR	OFF	2004/06/22 15:20
S48	1	"6201294".PN.	USPAT	OR	OFF	2004/06/22 15:20
S49	1	"6204554".PN.	USPAT	OR	OFF	2004/06/22 15:21
S50	1	"6208020".PN.	USPAT	OR	OFF	2004/06/22 15:21
S51	1	"6208023".PN.	USPAT	OR	OFF	2004/06/22 15:21
S52	1	"6281568".PN.	USPAT	OR	OFF	2004/06/22 15:21
S53	1	"6319753".PN.	USPAT	OR	OFF	2004/06/22 15:23
S54	1	"5389739".PN.	USPAT	OR	OFF	2004/06/22 15:24
S55	1	"5578871".PN.	USPAT	OR	OFF	2004/06/22 15:24
S56	1	"6303985".PN.	USPAT	OR	OFF	2004/06/22 15:24
S57	1	"4712129".PN.	USPAT	OR	OFF	2004/06/22 15:26
S58	1	"4803540".PN.	USPAT	OR	OFF	2004/06/22 15:26

S59	30	"5214307"	USPAT	OR	OFF	2004/06/22 15:31
S60	1	"4258381".PN.	USPAT	OR	OFF	2004/06/22 15:29
S61	1	"4857989".PN.	USPAT	OR	OFF	2004/06/22 15:29
S62	1	"5081520".PN.	USPAT	OR	OFF	2004/06/22 15:31
S63	11	"5864174"	USPAT	OR	OFF	2004/06/22 15:36
S64	2233	257/676	USPAT	OR	OFF	2004/06/22 15:36
S65	1940	257/676 and (wir\$3)	USPAT	OR	ON	2004/06/22 15:38
S66	1	"4994895".PN.	USPAT	OR	OFF	2004/06/22 15:42
S67	1	"5001542".PN.	USPAT	OR	OFF	2004/06/22 15:43
S68	1	"5001547".PN.	USPAT	OR	OFF	2004/06/22 15:43
S69	1	"5019673".PN.	USPAT	OR	OFF	2004/06/22 15:43
S70	1	"5045151".PN.	USPAT	OR	OFF	2004/06/22 15:43
S71	1	"4612564".PN.	USPAT	OR	OFF	2004/06/22 17:18
S72	1	"4633583".PN.	USPAT	OR	OFF	2004/06/22 17:19
S73	1	"5053855".PN.	USPAT	OR	OFF	2004/06/22 17:19
S74	1	"5147821".PN.	USPAT	OR	OFF	2004/06/22 17:19
S75	1	"5302849".PN.	USPAT	OR	OFF	2004/06/22 17:19
S76	1	"5367766".PN.	USPAT	OR	OFF	2004/06/22 17:19
S77	1	"5512781".PN.	USPAT	OR	OFF	2004/06/22 17:20
S78	1	"5527743".PN.	USPAT	OR	OFF	2004/06/22 17:20
S79	943	438/112	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/22 17:46
S80	363	438/117	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/22 18:04
S81	1618	438/123	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/22 18:46
S82	1187	438/124	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/22 19:08
S83	1628	438/127	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/22 19:27

S84	3151	257/666	USPAT	OR	ON	2004/06/22 19:28
S85	3167	257/676	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/22 19:54
S86	4566	257/787	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/23 11:29
S87	3904	257/778	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/23 11:32
S88	3388	257/778	USPAT	OR	OFF	2004/06/23 11:32
S89	2754	257/778 and solder	USPAT	OR	OFF	2004/06/23 11:32
S90	610	257/778 and solder with (big\$3 or larg\$2)	USPAT	OR	OFF	2004/06/23 11:55
S91	1327	257/777 and solder	USPAT	OR	OFF	2004/06/23 11:56
S92	1585	257/777 and (solder or ball or bump)	USPAT	OR	ON	2004/06/23 19:16
S93	45	257/777 and (solder or ball or bump)	JPO	OR	ON	2004/06/23 12:56
S94	1622	257/686 and (solder or ball or bump)	USPAT; JPO	OR	ON	2004/06/23 12:58
S95	9	"6297960"	USPAT	OR	OFF	2004/06/23 15:56
S96	1	"4996587".PN.	USPAT	OR	OFF	2004/06/23 18:59
S97	1	"5107328".PN.	USPAT	OR	OFF	2004/06/23 18:59
S98	1	"5247423".PN.	USPAT	OR	OFF	2004/06/23 18:59
S99	1	"5444296".PN.	USPAT	OR	OFF	2004/06/23 18:59
S100	1	"5646828".PN.	USPAT	OR	OFF	2004/06/23 19:00
S101	1	"5652463".PN.	USPAT	OR	OFF	2004/06/23 19:00
S102	1	"5656856".PN.	USPAT	OR	OFF	2004/06/23 19:00
S103	1	"5674785".PN.	USPAT	OR	OFF	2004/06/23 19:00
S104	1	"5677566".PN.	USPAT	OR	OFF	2004/06/23 19:00
S105	1	"5677566".PN.	USPAT	OR	OFF	2004/06/23 19:00
S106	1	"5808878".PN.	USPAT	OR	OFF	2004/06/23 19:00

S10 7	1	"5811879".PN.	USPAT	OR	OFF	2004/06/23 19:01
S10 8	1	"5838546".PN.	USPAT	OR	OFF	2004/06/23 19:01
S10 9	1	"5898224".PN.	USPAT	OR	OFF	2004/06/23 19:01
S11 0	1	"5952611".PN.	USPAT	OR	OFF	2004/06/23 19:01
S11 1	1	"5969426".PN.	USPAT	OR	OFF	2004/06/23 19:01
S11 2	1	"5973403".PN.	USPAT	OR	OFF	2004/06/23 19:01
S11 3	1	"5982038".PN.	USPAT	OR	OFF	2004/06/23 19:01
S11 4	1	"5994166".PN.	USPAT	OR	OFF	2004/06/23 19:01
S11 5	1	"6005778".PN.	USPAT	OR	OFF	2004/06/23 19:02
S11 6	1	"6013948".PN.	USPAT	OR	OFF	2004/06/23 19:02
S11 7	1	"6020629".PN.	USPAT	OR	OFF	2004/06/23 19:02
S11 8	1	"6051878".PN.	USPAT	OR	OFF	2004/06/23 19:03
S11 9	1	"6081023".PN.	USPAT	OR	OFF	2004/06/23 19:03
S12 0	1	"6087717".PN.	USPAT	OR	OFF	2004/06/23 19:03
S12 1	1	"6093969".PN.	USPAT	OR	OFF	2004/06/23 19:03
S12 2	1	"6181002".PN.	USPAT	OR	OFF	2004/06/23 19:03
S12 3	1	"6262488".PN.	USPAT	OR	OFF	2004/06/23 19:03
S12 4	1	"6265771".PN.	USPAT	OR	OFF	2004/06/23 19:03
S12 5	1	"6316727".PN.	USPAT	OR	OFF	2004/06/23 19:04
S12 6	1	"6388336".PN.	USPAT	OR	OFF	2004/06/23 19:04
S12 7	0	"2001/0015485".PN.	USPAT	OR	OFF	2004/06/23 19:04
S12 8	54	"5994166"	USPAT	OR	OFF	2004/06/23 19:04
S12 9	383	257/777 and (solder or ball or bump) and (capacitor or resistor)	USPAT	OR	ON	2004/06/23 21:16

S13 0	26	(257/777 or 257/686) and (solder or ball or bump) and (silicon or "Si") near (die or chip or semiconductor or IC) with memory	USPAT	OR	ON	2004/06/23 21:19
S13 1	207	(257/777 or 257/686) and (solder or ball or bump) and (silicon or "Si") near (die or chip or semiconductor or IC) and memory	USPAT	OR	ON	2004/06/23 21:19
S13 2	2457	"20010008482".pn. or "20010036063".pn. or "20020075662" "20020176233" "3,746,934" "4,773,868" "5,130, 894" "5,172,303" "5,222,014" "5, 334,875" "5", "394,303"	US-PGPUB; USPAT	OR	OFF	2004/11/05 17:58
S13 3	11	"20010008482".pn. or "20010036063".pn. or "20020075662".pn. or "20020176233".pn. or "3746934". pn. or "4773868".pn. or "5130894".pn. or "5172303".pn. or "5222014".pn. or "5334875". pn. or "5394303".pn.	US-PGPUB; USPAT	OR	OFF	2004/11/05 18:06
S13 4	42	"5,434,745".pn. or "5,455,385". pn. or "5,502,667".pn. or "5,544, 017".pn. or "5,586,010".pn. or "5, 666,272".pn. or "5,699,234".pn. or "5,701,233".pn. or "5,702,984". pn. or "5,712,768".pn. or "5,715, 144"	US-PGPUB; USPAT	OR	OFF	2004/11/05 18:07
S13 5	11	"5,434,745".pn. or "5,455,385". pn. or "5,502,667".pn. or "5,544, 017".pn. or "5,586,010".pn. or "5, 666,272".pn. or "5,699,234".pn. or "5,701,233".pn. or "5,702,984". pn. or "5,712,768".pn. or "5,715, 144".pn.	US-PGPUB; USPAT	OR	OFF	2004/11/05 18:12
S13 6	10	"5,721,671".pn. or "5,748,452". pn. or "5,781,415".pn. or "5,783, 870".pn. or "5,857,858".pn. or "5, 898,575".pn. or "5,907,903".pn. or "5,963,430".pn. or 5,9t7,640. pn. or "6,014,316".pn. or "6,049, 467".pn.	US-PGPUB; USPAT	OR	OFF	2004/11/05 18:13
S13 7	11	"5,721,671".pn. or "5,748,452". pn. or "5,781,415".pn. or "5,783, 870".pn. or "5,857,858".pn. or "5, 898,575".pn. or "5,907,903".pn. or "5,963,430".pn. or "5,977,640". pn. or "6,014,316".pn. or "6,049, 467".pn.	US-PGPUB; USPAT	OR	OFF	2004/11/05 18:18

S13 8	11	"6,093,029".pn. or "6,125,039".pn. or "6,133,626".pn. or "6,163,462".pn. or "6,180,881".pn. or "6,195,268".pn. or "6,222,265".pn. or "6,265,772".pn. or "6,297,960".pn. or "6,331,939".pn. or "6,381,141".pn.	US-PGPUB; USPAT	OR	OFF	2004/11/05 18:24
S13 9	4090	"6,477,058".pn. or "6,504,241".pn. or 257/778 "525,943".pn. or "6,525,945".pn. or "6,529,385".pn. or "6,542,393".pn. or "6,545,868".pn. or "6,549,421".pn. or "6,583,503".pn.	US-PGPUB; USPAT	OR	OFF	2004/11/05 18:25
S14 0	9	"6477058".pn. or "6504241".pn. or "6525943".pn. or "6525945".pn. or "6529385".pn. or "6542393".pn. or "6545868".pn. or "6549421".pn. or "6583503".pn.	US-PGPUB; USPAT	OR	OFF	2004/11/05 18:25
S14 1	2822	257/686	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 17:07
S14 2	2363	257/686	USPAT	OR	OFF	2005/04/06 13:17
S14 3	1646	257/686 and (ball or bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 17:39
S14 4	2	"08335407"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 14:48
S14 5	1562	anistropic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 14:49
S14 6	252	anisotropic same (bead or particle or ball) with coat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 14:51

S14 7	43	anisotropic same (bead or particle or ball) with coat\$3 with (dielectric or insulating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 14:54
S14 8	4	anisotropic same (conductive or metal) with (bead or particle or ball) with (dielectric or insulating) with shell	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 14:54
S14 9	4	anisotropic same (conductive or metal) with (bead or particle or core or ball) with (dielectric or insulating) with shell	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 14:55
S15 0	14	anisotropic and (conductive or metal) with (bead or particle or core or ball) with (dielectric or insulating) with shell	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 14:56
S15 1	17	anisotropic and (conduct\$3 or metal\$4) with (bead or particle or core or ball) with (dielectric or insulating) with shell	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 15:57
S15 2	7	"6515356"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 15:57
S15 3	1176	S141 not S143	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 17:39
S15 4	2674	257/777	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 18:39

S15 5	1693	257/777 and (ball or bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 18:08
S15 6	0	S155 not S154	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 18:08
S15 7	981	S154 not S155	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 18:08
S15 8	4307	257/778	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 19:18
S15 9	2267	257/786	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 19:45
S16 0	2048	257/780	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 20:03
S16 1	2	"5995379".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 19:59
S16 2	1067	257/781	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 20:27

S16 3	2332	257/712	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 21:15
S16 4	1803	257/713	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/06 21:15
S16 5	2473	257/678	USPAT	OR	OFF	2005/04/07 19:21
S16 6	93090	(semiconductor or die or chip or IC) with (both or double or dual)	USPAT	OR	ON	2005/04/07 19:22
S16 7	1677	(semiconductor or die or chip or IC) with (dual) and (ball or bump)	USPAT	OR	ON	2005/04/07 19:22
S16 8	103	"6020629"	USPAT	OR	OFF	2005/04/07 22:49